

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: Examiner: Nguyen, Khiem D.  
Toshikazu Okubo et al.

Serial No. 10/550,153 Art Unit: 2823

Filed: September 20, 2005 Confirmation No.: 1053

Title: Method for Analyzing Copper Electroplating Solution, Apparatus for the Analysis, and Method for Fabricating Semiconductor Product

## **RESPONSE TO OFFICE ACTION**

Dear Examiner Nguyen:

This is a response to the Office Action dated November 27, 2009, which has a shortened statutory period for reply that ends on February 27, 2010. Please amend the above-identified application as follows.

**Claims** begin on page 2 of this paper.

**Remarks** begin on page 11 of this paper.